Future of chip design revealed at ISPD

R. Colin Johnson
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PORTLAND, Ore. —Advances in the design and fabrication of semiconductors were unveiled here this week at the International Symposium on Physical Design (ISPD, April 13-16, 2008, Portland, Ore.). As the premier forum for sharing leading-edge results in chip-design methodologies, the ISPD also identifies future research trends years before they become commercialized. This year, topics ranged from the need for collaboration among chip makers at the 32-nanometer node, how logic-synthesis is solving problems with physical-synthesis, how radio-frequency interconnection strategies could enhance standard CMOS, to how the Taiwanese beat both the U.S. and Europeans in the ISPD Global Routing Contest.